

* Material Composition - nRF52832-CIAA (NSBDPHF46#C)

Material	Purpose	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogenous material	PPM	% weight of substance per package
Polybenzoxazole1	Dielectric	Proprietary	-----	0.07108	100%	10147	1.015%
Polybenzoxazole2	Dielectric	Proprietary	-----	0.06050	100%	8637	0.864%
RDL Seed Layer	Seed Layer	Ti	7440-32-6	0.00042	3.93%	60	0.006%
	Seed Layer	W	7440-33-7	0.00377	35.40%	538	0.054%
	Seed Layer	Cu	7440-50-8	0.00646	60.67%	922	0.092%
Copper	Interconnect	Cu	7440-50-8	0.12922	100%	18446	1.845%
UBM Seed Layer	Seed Layer	Ti	7440-32-6	0.00021	3.93%	30	0.003%
	Seed Layer	W	7440-33-7	0.00188	35.40%	269	0.027%
	Seed Layer	Cu	7440-50-8	0.00323	60.67%	461	0.046%
Copper	UBM	Cu	7440-50-8	0.14529	100%	20741	2.074%
Solder Ball	Interconnect	Sn	7440-31-5	1.52800	95.50%	218125	21.813%
	Interconnect	Ag	7440-22-4	0.06400	4.00%	9136	0.914%
	Interconnect	Cu	7440-50-8	0.00800	0.50%	1142	0.114%
Die	Circuit	Si	7440-21-3	4.98309	100%	711346	71.135%
Package Weight (mg):				7.01		% Total:	100%